0033-0694P

IN THE U.S. PATENT AND TRADEMARK OFFICE

SUMIKAWA, et al.

Conf.:2465

09/782,180

Group:

2814

Filed:

February 14, 2001

Examiner:

D. NGUYEN

For:

SEMICONDUCTOR DEVICE AND METHOD OF

MANUFACTURING THE SAME

REPLY UNDER 37 C.F.R. § 1.111

Assistant Commissioner for Patents Washington, DC 20231

April 30, 2002

Sir:

In reply to the Office Action mailed January 30, 2002, the following amendments and remarks are submitted.

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A semiconductor device comprising:

a semiconductor substrate having a surface provided with an external connection electrode and;

a surface opposite that with said external connection electrode, abrased with a mirror finish and reinforced with a back-surface reinforcement member.

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